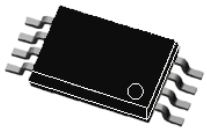
STC6NF30V

N-channel 30V - 0.020Ω - 6A - TSSOP8
2.5V-drive STripFET™ II Power MOSFET

General features

Type	V_{DSS}	$R_{DS(on)}$	I_D
STC6NF30V	30V	< 0.025 Ω (@ 4.5 V) < 0.030 Ω (@ 2.7 V)	6A

- Ultra low threshold gate drive (2.5V)
- Standard outline for easy automated surface mount assembly
- Double dice in common drain configuration

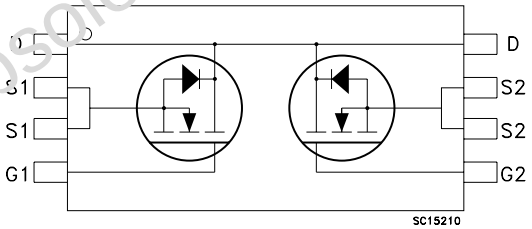


TSSOP8

Description

This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance.

Internal schematic diagram



Applications

- Switching application

Obsolete Product(s) - Obsolete Product(s)

Order code

Part number	Marking	Package	Packaging
STC6NF30V	C6NF30V	TSSOP8	Tape & reel

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2 Electrical characteristics 4

2.1 Electrical characteristics (curves) 6

3 Test circuit 9

4 Package mechanical data 10

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Obsolete Product(s) - Obsolete Product(s)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0)	30	V
V_{DGR}	Drain-gate voltage (R_{GS} = 20KΩ)	20	V
V_{GS}	Gate-source voltage	± 12	V
I_D	Drain current (continuous) at T_C = 25°C	6	A
I_D	Drain current (continuous) at T_C=100°C	3.8	A
I_{DM}(1)	Drain current (pulsed)	24	A
P_{TOT}	Total dissipation at T_C = 25°C	1.5	W
T_{stg}	Storage temperature	–55 to 150	°C
T_J	Max. Operating Junction Temperature	–55 to 150	°C

1. Pulse width limited by safe operating area

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thJ\text{-}PBC}$	Thermal resistance junction-PBC Max	100 (1)	°C/W
$R_{thJ\text{-}PBC}$	Thermal resistance junction-PBC Max	83.5 (2)	°C/W

1. When Mounted on FR-4 board with 1 inch^2 pad, 2 oz. of Cu. and t = 10 sec.
2. When Mounted on minimum recommended footprint

Obsolete Product(s) - Obsolete Product(s)

2 Electrical characteristics

(T_J = 25°C unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 250µA, V_{GS}= 0	30			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = Max rating, V_{DS} = Max rating @125°C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ±12V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250µA	0.6			V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS}= 4.5V, I_D= 3A V_{GS} =2.5V, I_D = 3A		0.020 0.025	0.025 0.030	Ω Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward transconductance	V_{DS} = 10V, I_D = 6A		18		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} =25V, f = 1 MHz, V_{GS} = 0		800 180 32		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} =15V, I_D = 6A V_{GS} = 2.5V *Figure 16 on page 9*		6.8 2.0 3.4	9	nC nC nC

1. Pulsed: pulse duration=300µs, duty cycle 1.5%

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 15V, I_D = 3A, R_G = 4.7Ω, V_{GS} = 2.5V *Figure 14 on page 9*		20 25 32 13		ns ns ns ns

Obsolete Product(s) - Obsolete Product(s)

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
I_{SD}	Source-drain current				6	A
I_{SDM}(1)	Source-drain current (pulsed)				24	A
V_{SD}(2)	Forward on voltage	I_{SD} = 6A, V_{GS} = 0			1.2	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 6A, di/dt = 100A/µs, V_{DD} = 15V, T_J = 150°C *Figure 16 on page 9*		25 21 1.7		ns µC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300µs, duty cycle 1.5%

Obsolete Product(s) - Obsolete Product(s)

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

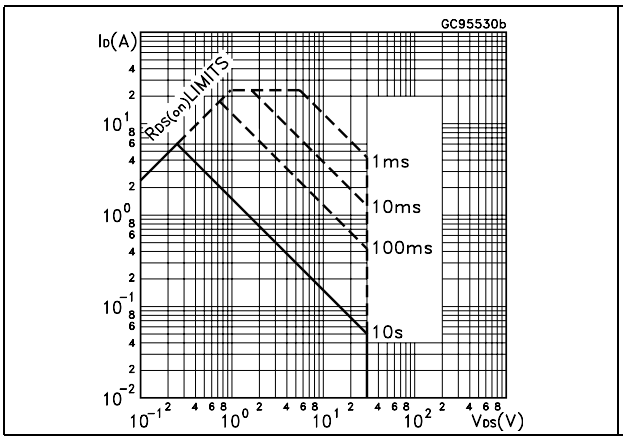


Figure 2. Thermal impedance

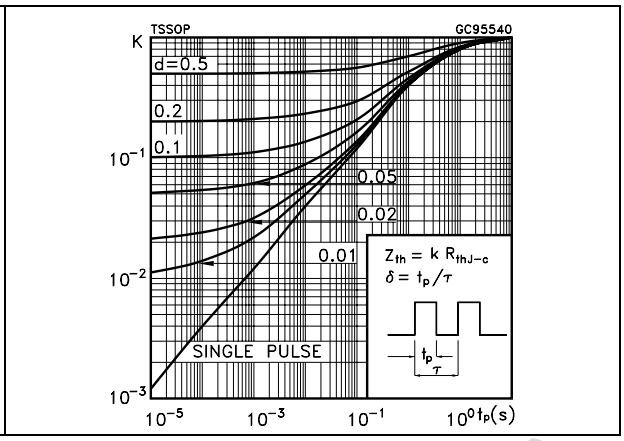


Figure 3. Output characteristics

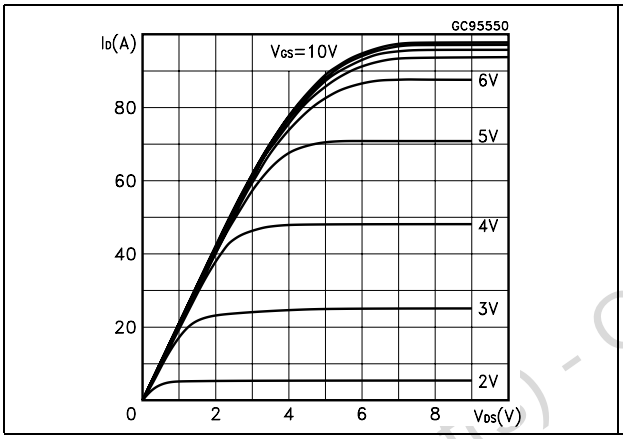


Figure 4. Transfer characteristics

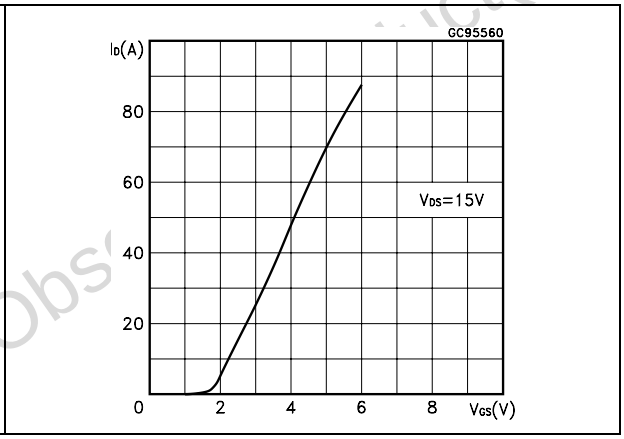


Figure 5. Transconductance

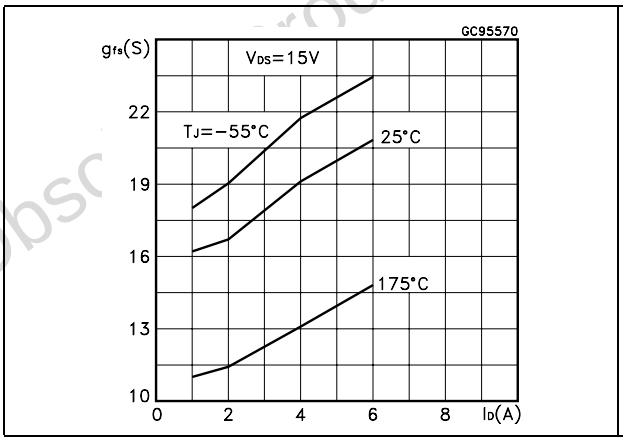
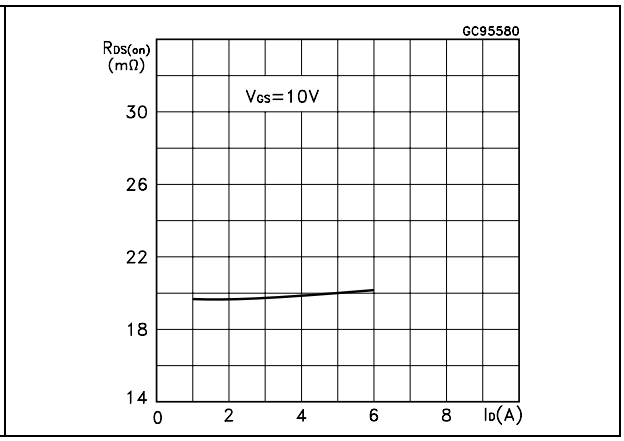


Figure 6. Static drain-source on resistance



Obsolete Product(s) - Obsolete Product(s)

Figure 7. Gate charge vs. gate-source voltage

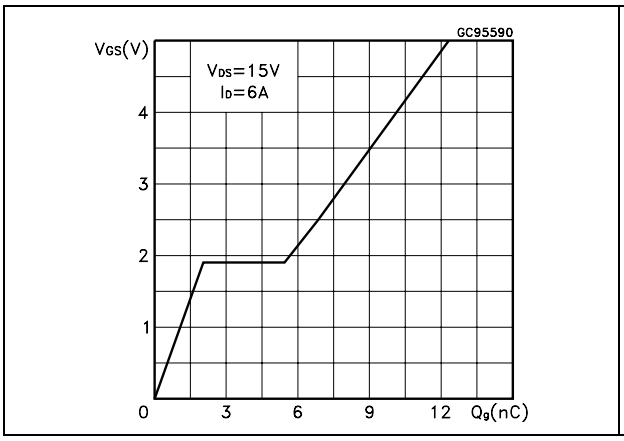


Figure 8. Capacitance variations

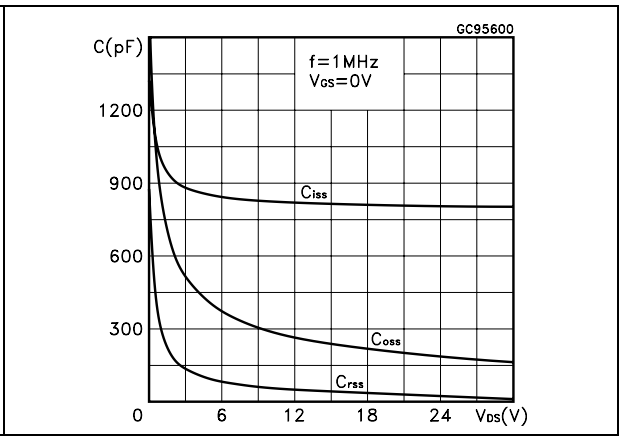


Figure 9. Normalized gate threshold voltage vs. temperature

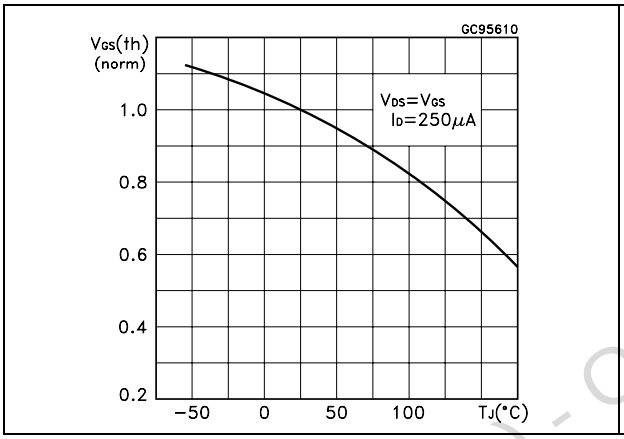


Figure 10. Normalized on resistance vs. temperature

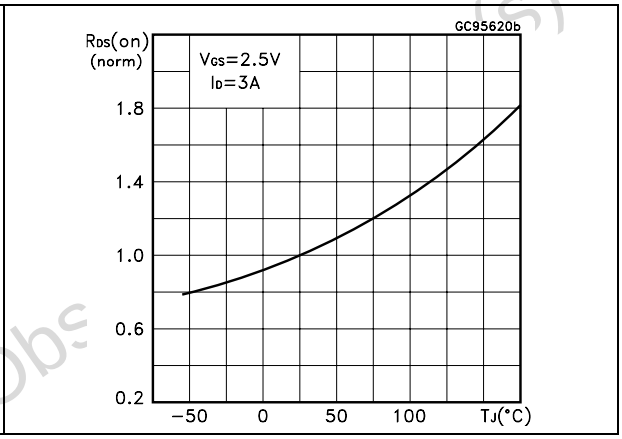


Figure 11. Source-drain diode forward characteristics

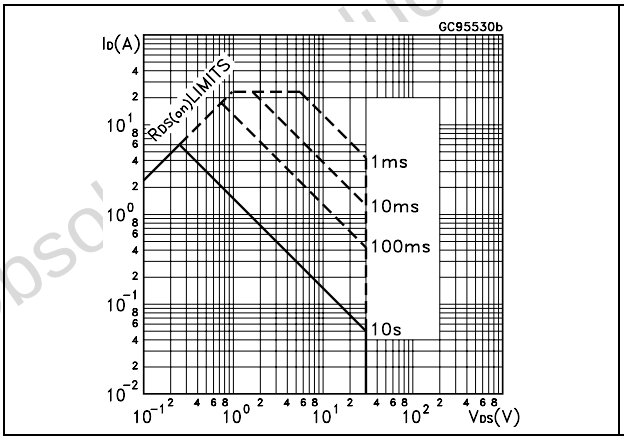
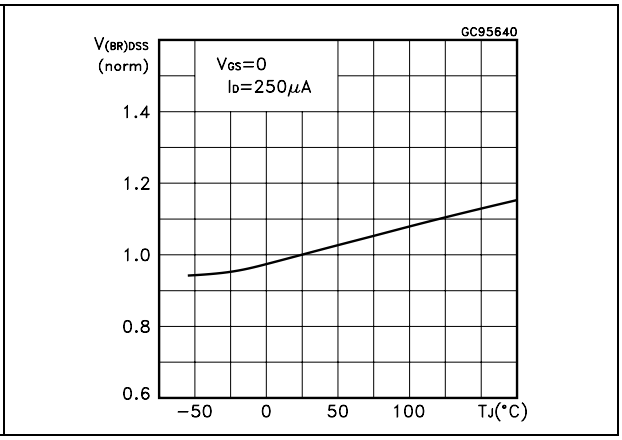
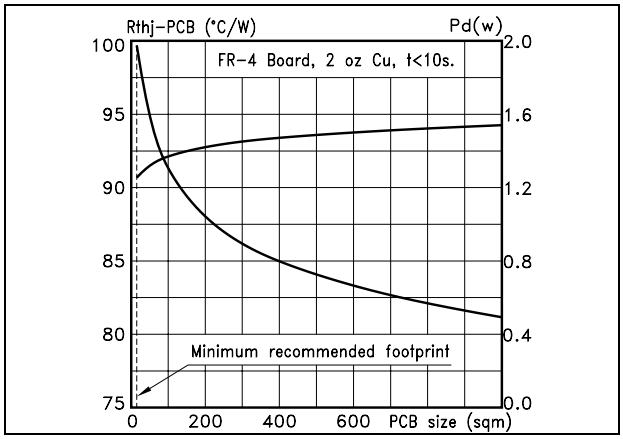


Figure 12. Normalized breakdown voltage temperature



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Figure 13. Thermal resistance and max power



Obsolete Product(s) - Obsolete Product(s)

3 Test circuit

Figure 14. Switching times test circuit for resistive load

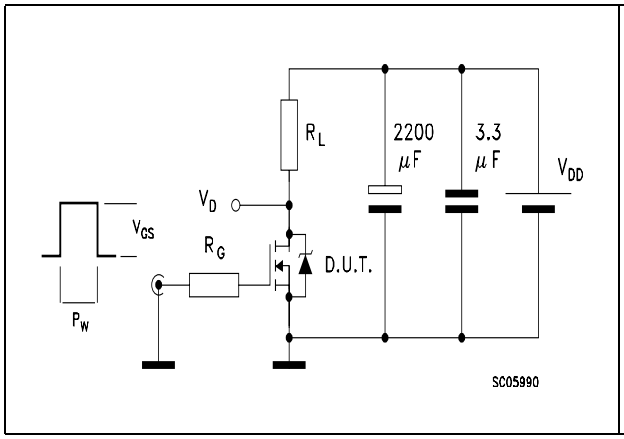


Figure 15. Gate charge test circuit

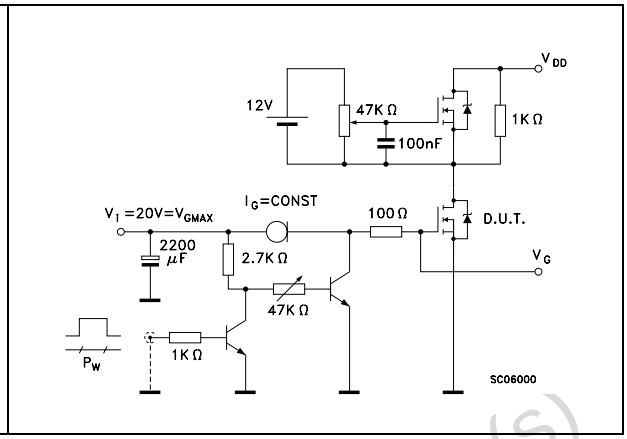
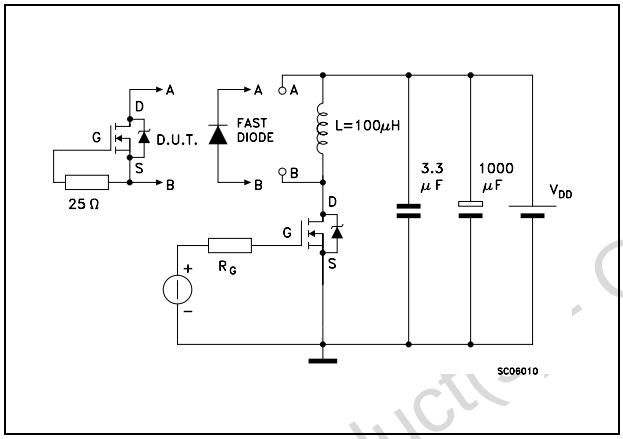


Figure 16. Test circuit for inductive load switching and diode recovery times



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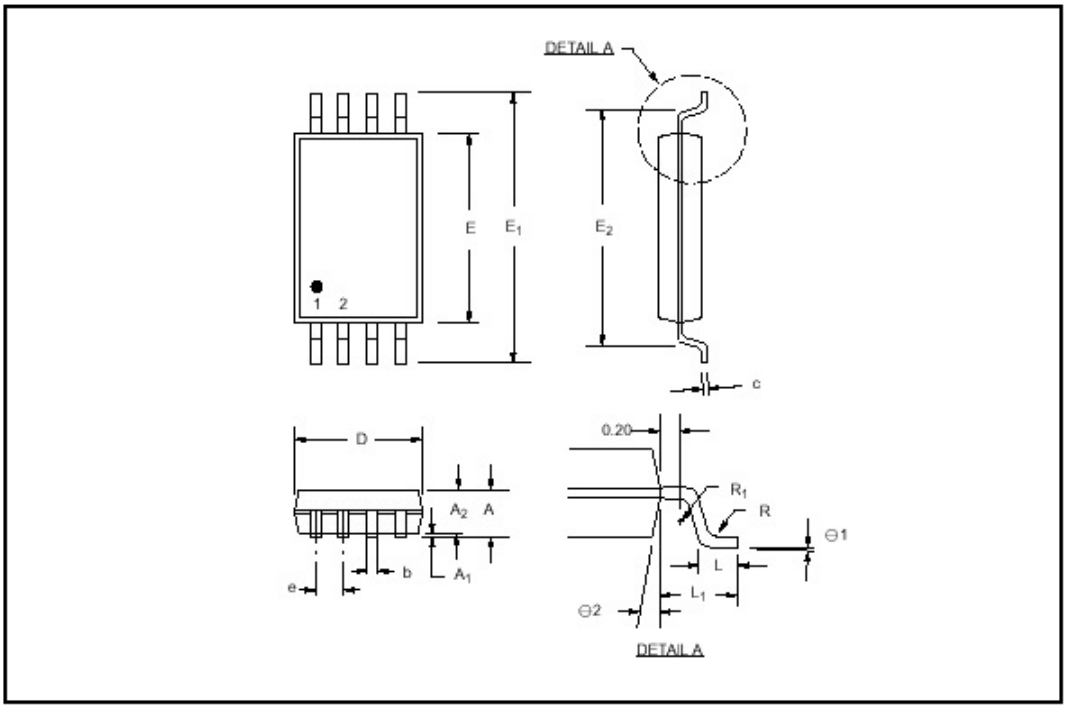
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

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TSSOP8 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	1.05		1.20	0.041		0.047
A1	0.05		0.15	0.002		0.006
A2	0.80		1.05	0.032		0.041
b	0.19		0.30	0.008		0.012
c		0.127			0.005	
D	2.90		3.10	0.114		0.122
E	4.30		4.50	0.170		0.177
E1	6.20		6.60	0.240		0.260
E2	5.14		5.24	0.202		0.206
e		0.65			0.025	
L	0.45		0.75	0.018		0.030
L1	0.90		1.10	0.0355		0.0433
R	0.09			0.004		
R1	0.09			0.004		
θ1	0°		8°	0°		8°
θ2	12°					



Obsole

5 Revision history

Table 7. Revision history

Date	Revision	Changes
21-Jun-2004	2	Complete document
03-Aug-2006	3	The document has been reformatted, SOA updated
01-Feb-2007	4	Typo mistake on first page

Obsolete Product(s) - Obsolete Product(s)

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